



UM10465

TEA1713 and TEA1795 demo board for 150 W all-in-one PC adapter

Rev. 1 — 28 September 2011

User manual

Document information

Info	Content
Keywords	TEA1713T, TEA1795T, 150 W, all-in-one PC adapter, GreenChip-SR, synchronous rectification, LLC, resonant, half-bridge, PFC, controller, converter, burst mode, power supply, demo board
Abstract	<p>The TEA1713T includes a Power Factor Correction (PFC) controller and a controller for a Half-Bridge resonant Converter (HBC).</p> <p>This user manual describes a 150 W resonant Switching Mode Power Supply (SMPS) for a typical all-in-one PC adapter design based on the TEA1713T and TEA1795T. The board provides an output of 19.5 V/7.7 A. It operates in normal mode for medium and high-power levels and in burst mode for low-power levels. Burst mode operation provides a reduction of power losses to increase performance.</p> <p>The efficiency at high power is well above 90 % and the no load power consumption is well below 500 mW.</p>



Revision history

Rev	Date	Description
v.1	20110928	first release

Contact information

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: salesaddresses@nxp.com

1. Introduction

WARNING

Lethal voltage and fire ignition hazard



The non-insulated high voltages that are present when operating this product, constitute a risk of electric shock, personal injury, death and/or ignition of fire.

This product is intended for evaluation purposes only. It shall be operated in a designated test area by personnel qualified according to local requirements and labor laws to work with non-insulated mains voltages and high-voltage circuits. This product shall never be operated unattended.

1.1 Scope of this document

This document describes the 150 W all-in-one PC adapter demo board using the TEA1713T and TEA1795T. A functional description is provided, supported by a set of measurements to show the all-in-one PC adapter characteristics.

1.2 TEA1713T

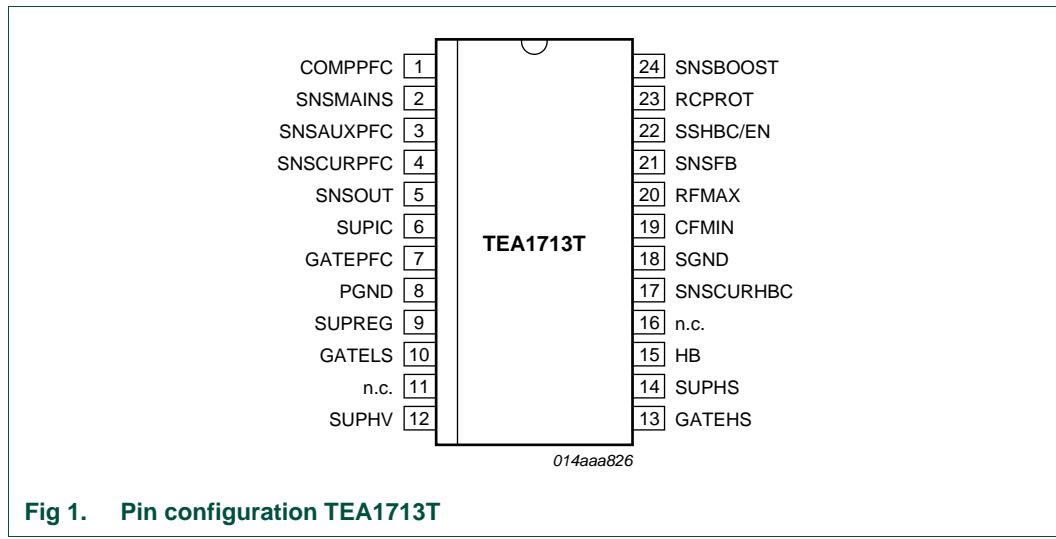
The TEA1713T integrates a controller for PFC and a controller for an HBC. It provides the drive function for the discrete MOSFET of the up-converter and for the two discrete power MOSFETs in a resonant half-bridge configuration.

The resonant controller part is a high-voltage controller for a Zero Voltage Switching (ZVS) LLC resonant converter. It includes a high-voltage level shift circuit and several protection features such as OverCurrent Protection (OCP), Open-Loop Protection (OLP), Capacitive Mode Protection (CMP) and a general purpose latched protection input.

In addition to the resonant controller, the TEA1713T contains a PFC controller. The efficient operation of the PFC is obtained by functions such as quasi-resonant operation at high-power levels and quasi-resonant operation with valley skipping at lower power levels. OCP, OverVoltage Protection (OVP) and demagnetization sensing, ensures safe operation in all conditions.

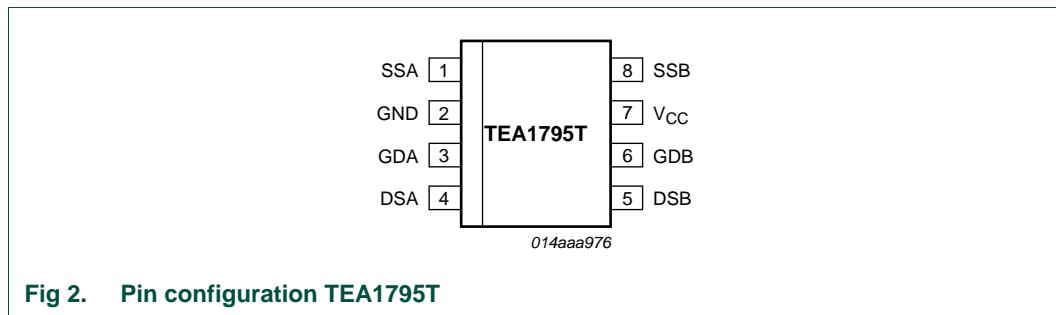
The proprietary high-voltage BCD power logic process makes direct start-up from the rectified universal mains voltage in an efficient way possible. A second low voltage Silicon-On-Insulator (SOI) IC is used for accurate, hi-speed protection functions and control.

The combination of PFC and a resonant controller in one IC makes the TEA1713T suitable for all-in-one PC adapters.



1.3 TEA1795T

The TEA1795T GreenChip-SR is a synchronous rectification control IC that needs no external components to tune the timing. Used in all-in-one PC adapter designs, the GreenChip-SR offers a wide V_{CC} operating range between 8.5 V and 38 V, minimizing the number of external components required and enabling simpler designs. In addition, the high driver output voltage (10 V) makes the GreenChip-SR compatible with all MOSFET brands.



1.4 Setup of the 150 W all-in-one PC adapter

The board can operate at a mains input voltage of between 90 V and 264 V (universal mains).

The demo board contains two subcircuits:

- A PFC of BCM-type
- An HBC of resonant LLC-type

Both converters are controlled by the TEA1713T.

At low-power levels, the converters operate in burst mode to reduce power losses.

The purpose of the demo board is to demonstrate the operation of the TEA1713T and TEA1795T in a single output supply including burst mode operation. The performance is according today's general standards and can be used as a starting point for further development.



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Fig 3. TEA1713T demo board 150 W all-in-one PC adapter

1.5 Input and output properties

Table 1. Input data

Symbol	Description	Conditions	Specification	Unit
V_i	input voltage	AC	90 to 264	V (RMS)
f_i	input frequency	-	47 to 60	Hz
$P_{i(\text{no load})}$	no load input power	230 V, 50 Hz	< 500	mW

Table 2. Output data

Symbol	Description	Conditions	Specification	Unit
V_o	output voltage	-	19.5	V
$V_{o(\text{ripple})(\text{p-p})}$	peak-to-peak ripple voltage	20 MHz bandwidth	< 150	mV
I_o	output current	continuous	0 to 7.7	A

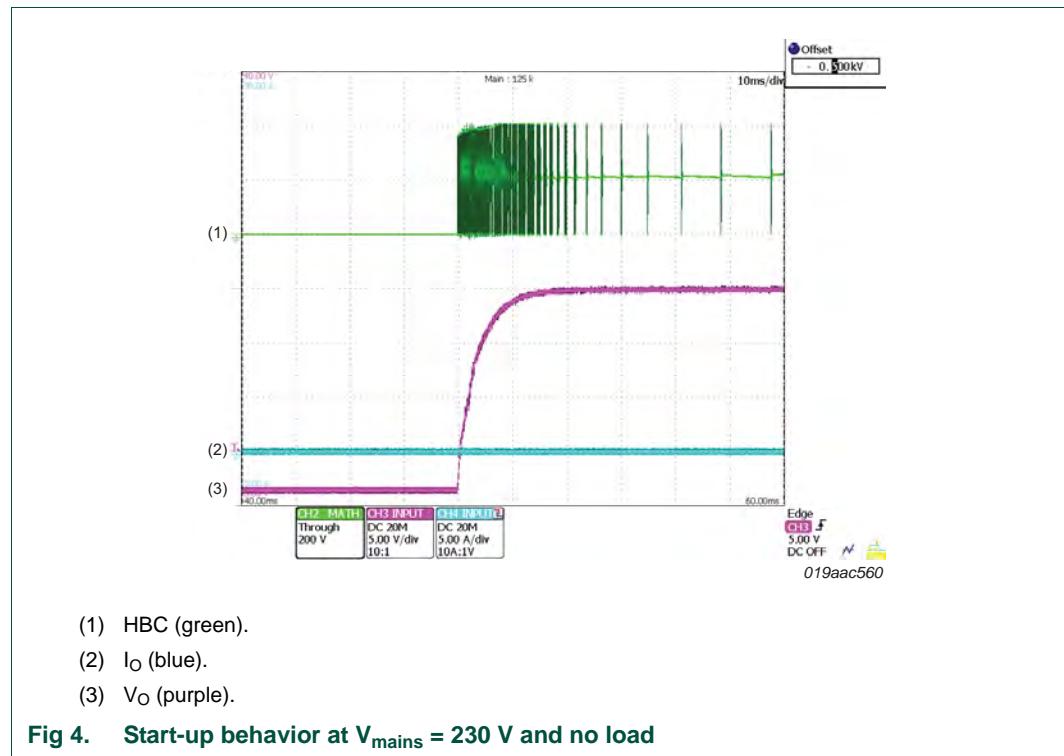
2. Measurements

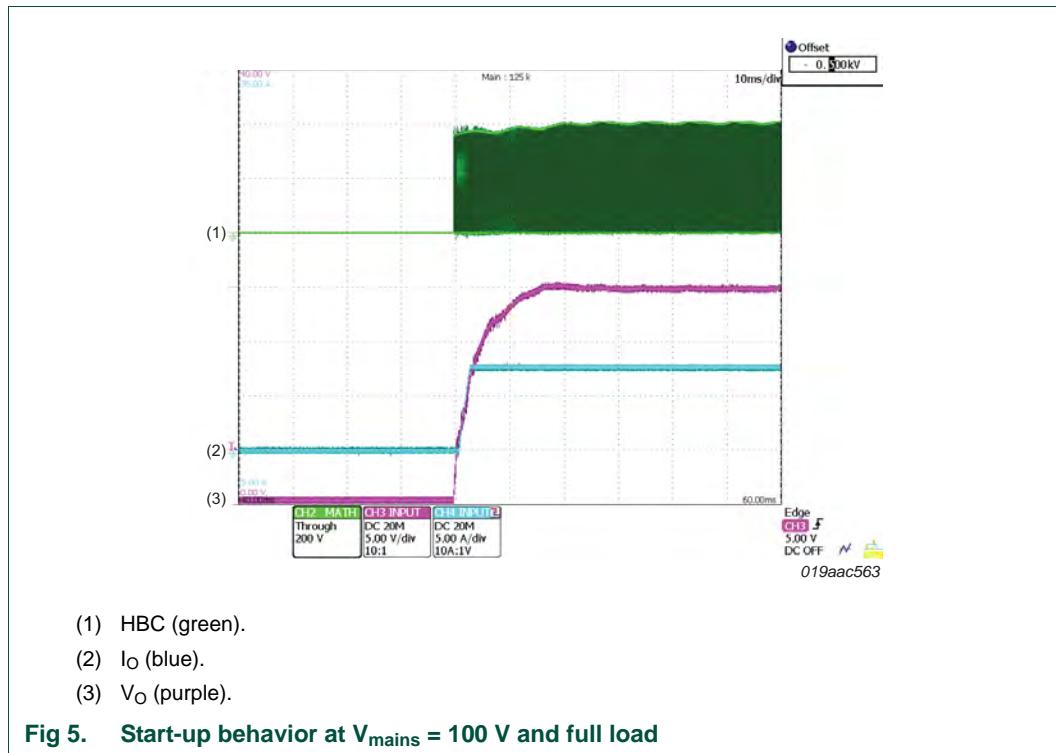
2.1 Test facilities

- Oscilloscope: Yokogawa DL1640L
- AC power source: Agilent 6812B
- Electronic load: Agilent 6063B
- Digital power meter: Yokogawa WT210

2.2 Start-up behavior

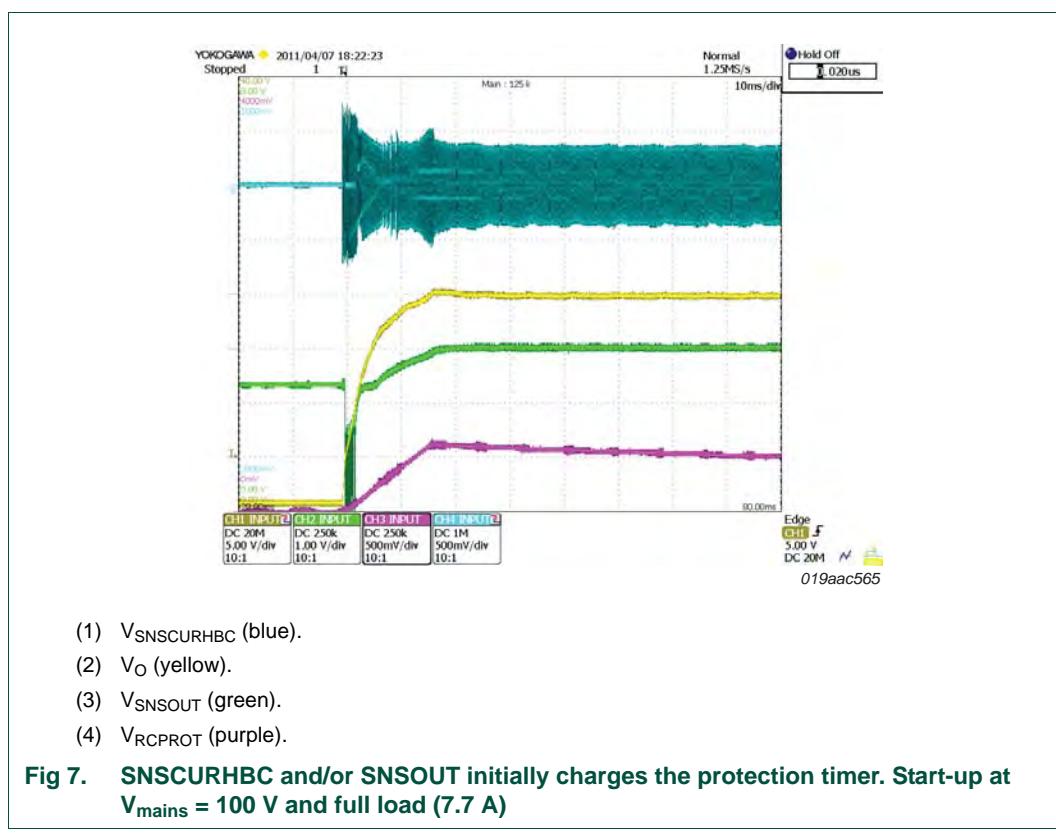
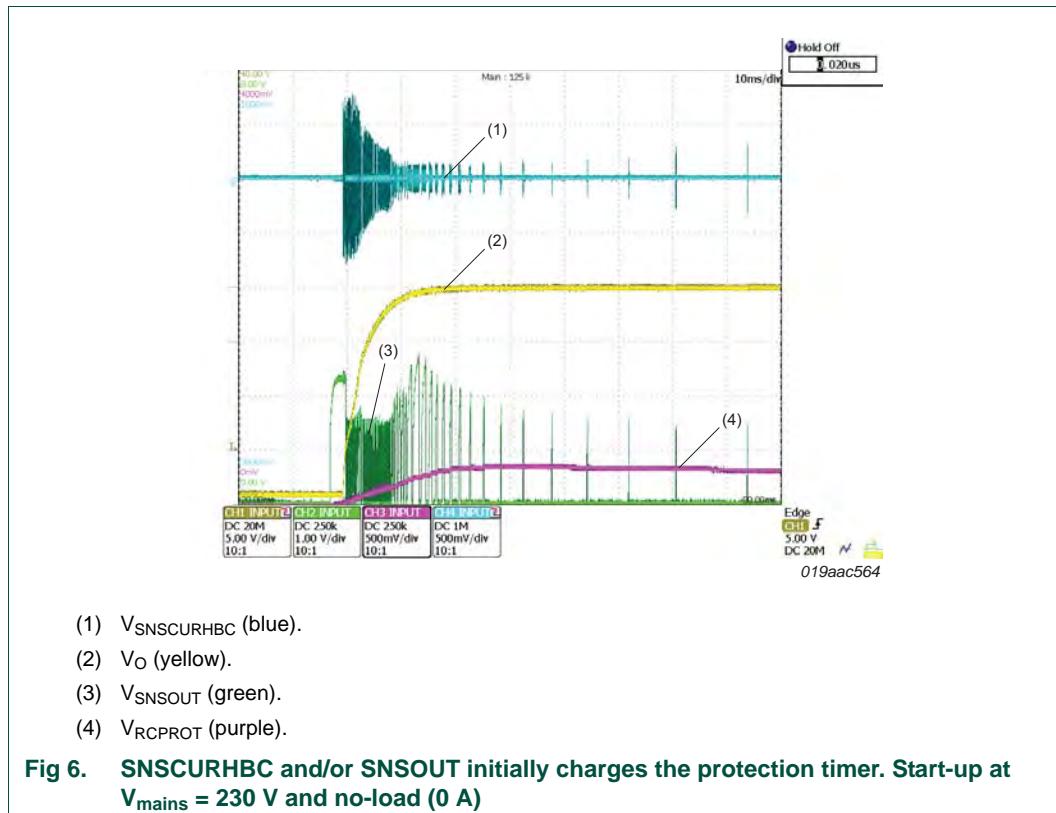
The rise time of the output voltage (measured from 10 % to 90 % point of the nominal output) is between 8 ms to 15 ms, depending on the output current load.





2.3 Protection levels on SNSCURHBC and SNSOUT during start-up

During start-up the voltage at pin RCPROT (protection timer) always rises. SNSCURHBC detects the initial high primary current and SNSOUT starts at a low voltage. After the first switching cycles the levels become normal for operation and the charging of RCPROT ends. The voltage level on RCPROT now decreases to zero again by the external discharge resistor that is part of the RCPROT system. During normal start-up the initial charging of RCPROT must not trigger a protection (4 V level).



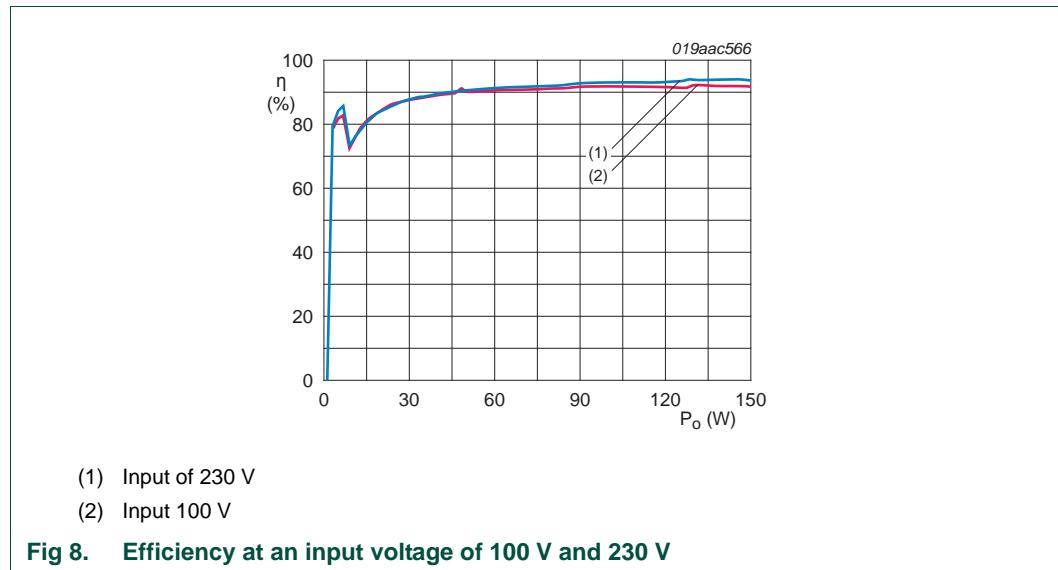
2.4 Efficiency

2.4.1 Efficiency characteristics

Efficiency measurements were made measuring the output voltage on the board (not taking into account the losses in an output connection cable).

Table 3. Efficiency results

Conditions	Energy star 2.0 efficiency requirement (%)	Efficiency (%)				
		Average	25 % load	50 % load	75 % load	100 % load
100 V, 60 Hz	> 87	91.2	89.1	91.4	92.1	92.3
230 V, 50 Hz	> 87	92.2	89.3	92.6	93.2	93.6



2.4.2 Power Factor Correction (PFC)

Table 4. Power Factor correction (PFC)

Condition	Energy Star 2.0 requirement	Output power (W)	Power factor
90 V, 60 Hz	-	150	0.99
100 V, 60 Hz	-	150	0.99
115 V, 60 Hz	≥ 0.9	150	0.99
230 V, 50 Hz	-	150	0.95
264 V, 50 Hz	-	150	0.92

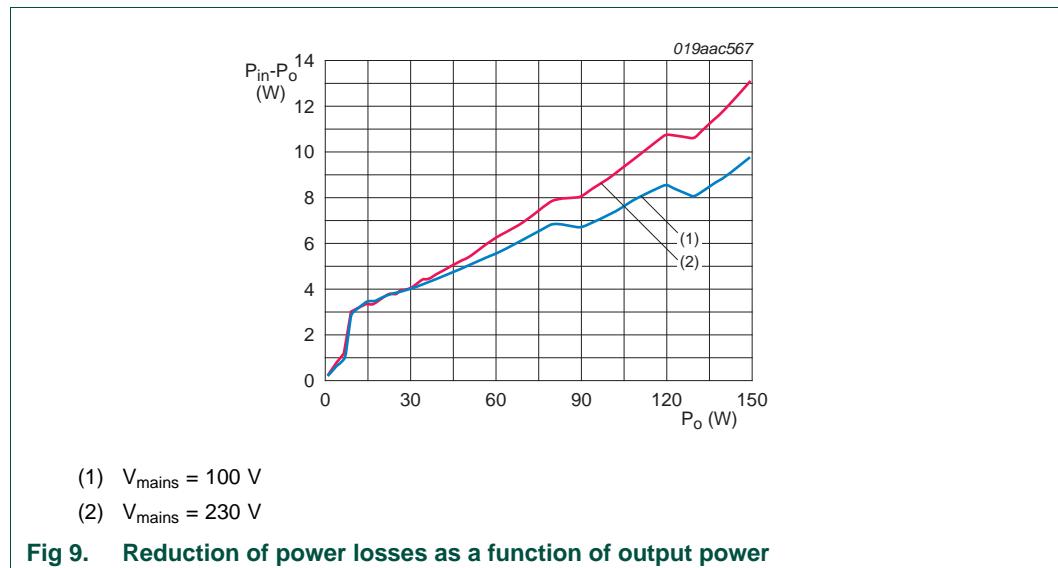
2.4.3 No-load power consumption

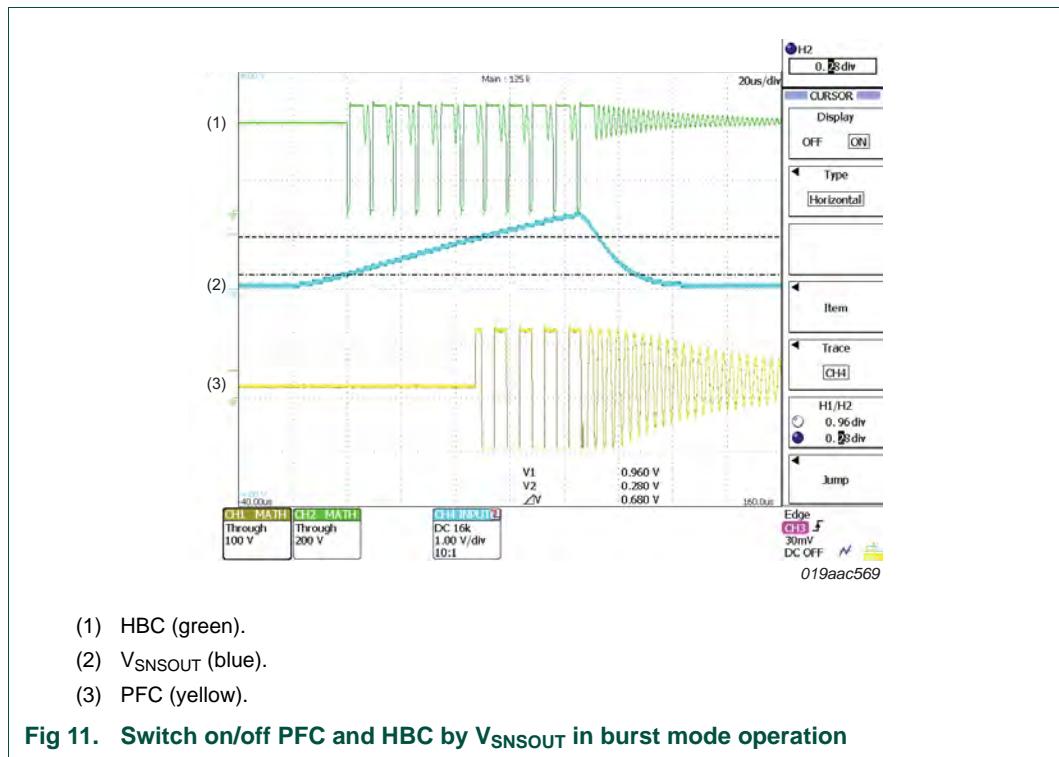
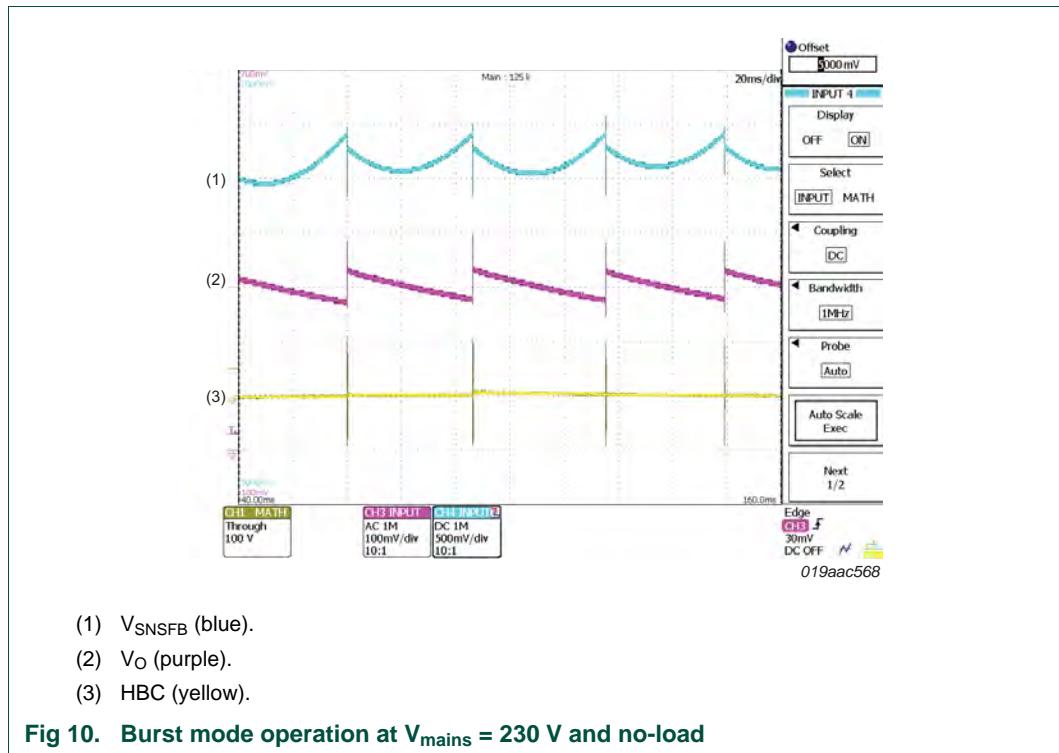
Table 5. Output voltage and power consumption at no-load

Condition	Energy Star 2.0 requirement (mW)	Output voltage (V)	No load power consumption (mW)
90 V, 60 Hz	≤ 500 mW	19.5	220
100 V, 60 Hz	≤ 500 mW	19.5	230
115 V, 60 Hz	≤ 500 mW	19.5	240
230 V, 50 Hz	≤ 500 mW	19.5	250
264 V, 50 Hz	≤ 500 mW	19.5	260

2.5 Behavior in burst mode operation

In order to reach the no load power consumption requirements (see [Section 2.4.3](#)), burst mode operation is implemented to improve the performance at low output load. For the demo board burst mode is active below approximately 5 W output power.

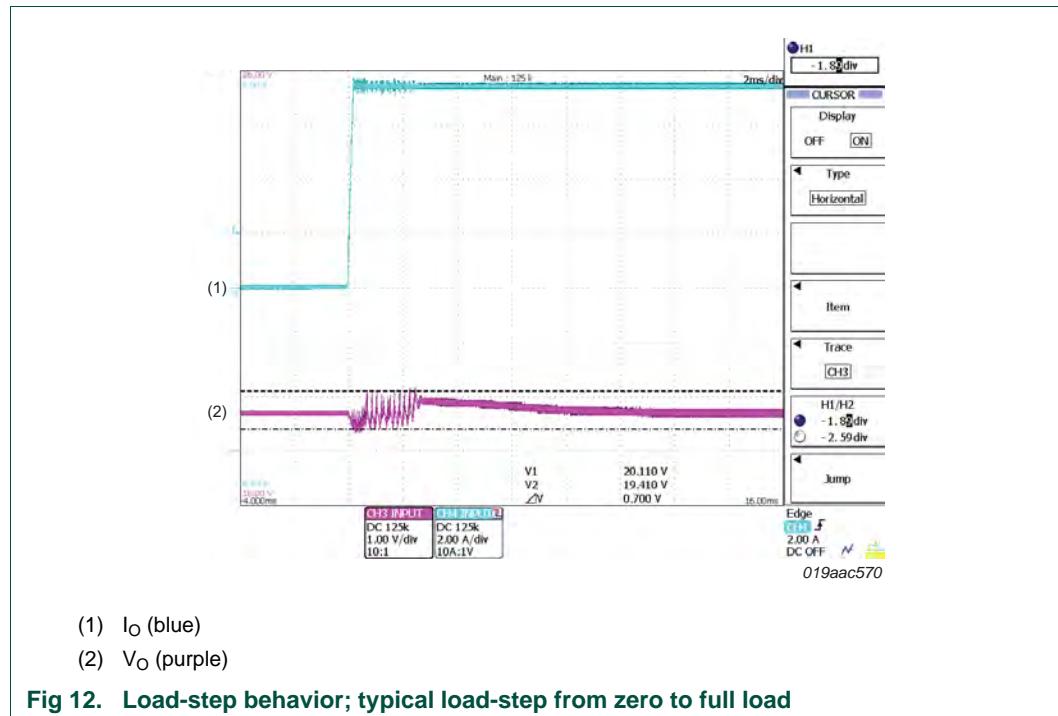




The interruptive character of burst mode can lead to the generation of unwanted audible noise. As the supply in burst mode only operates at low-power levels, audible noise levels are low.

2.6 Transient response

Normal load transients lead to a ripple on the output voltage of < 800 mV.



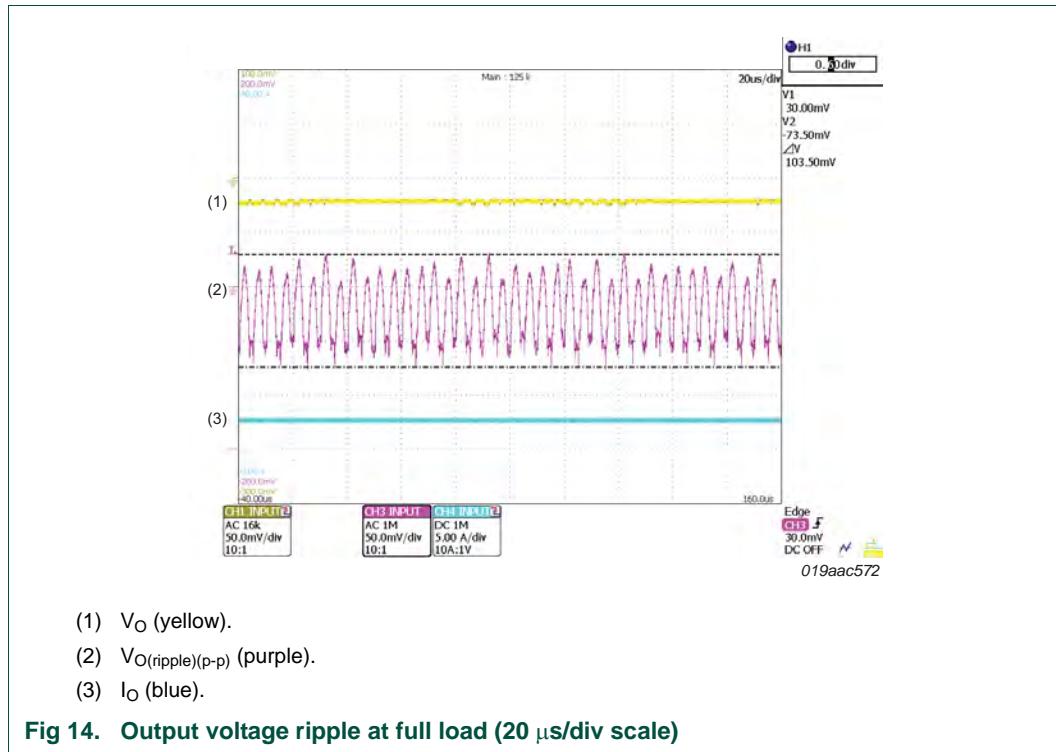
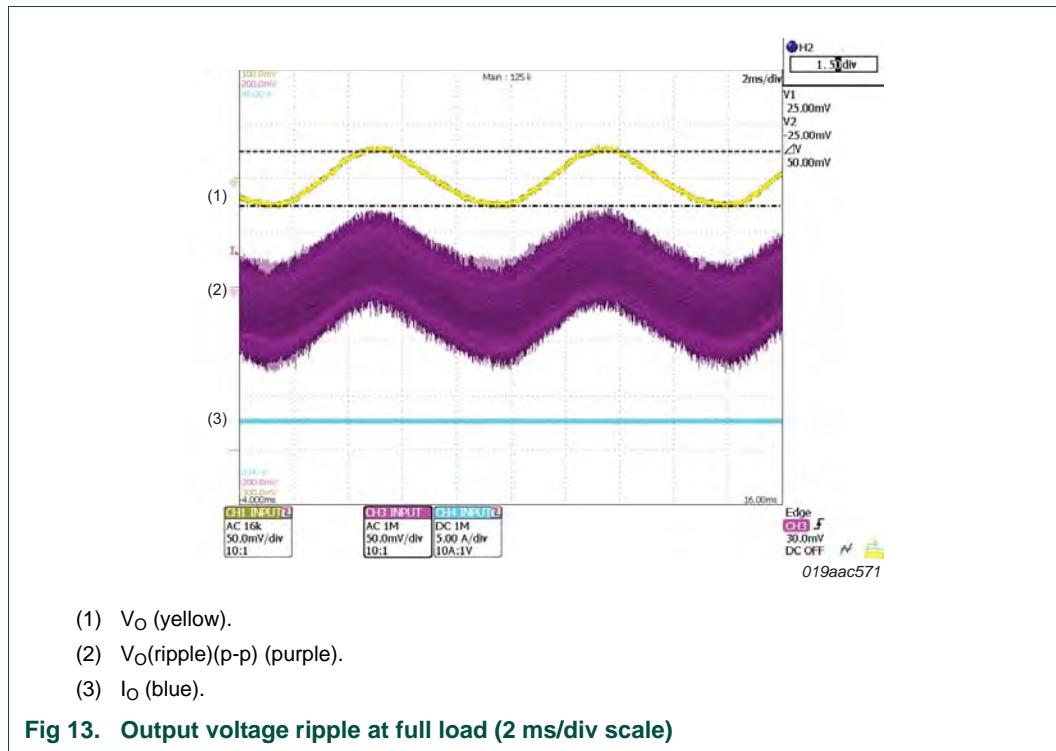
2.7 Output ripple voltage and noise

Ripple and noise are measured at full output load, buffered with a 10 μF capacitor in parallel with a high-frequency 0.1 μF capacitor.

The varying input voltage of the resonant converter causes a frequency component in the output ripple voltage that is related to the mains voltage frequency: 50 Hz or 60 Hz. The switching frequency of the resonant converter causes the other component in the output ripple voltage.

Table 6. Ripple and noise test results

Mains voltage	Mains frequency	Output power	Ripple frequency	Voltage ripple
90 V to 264 V	50 Hz or 60 Hz	150 W	50 Hz or 60 Hz	52 mV (p-p)
90 V to 264 V	50 Hz or 60 Hz	150 W	215 kHz	68 mV (p-p)



2.8 OverPower Protection (OPP)

Tested with a higher current (dynamic overload) on the output voltage, the OPP is activated when the current exceeds 10 A (195 W). This corresponds to a load condition that is 30 % higher than the rated power for continuous use. The OPP is detected by the SNSCURHBC function of the TEA1713T that monitors the primary resonant current. When the voltage on the SNSCURHBC pin exceeds 0.5 V (or -0.5 V) the protection timer is started.

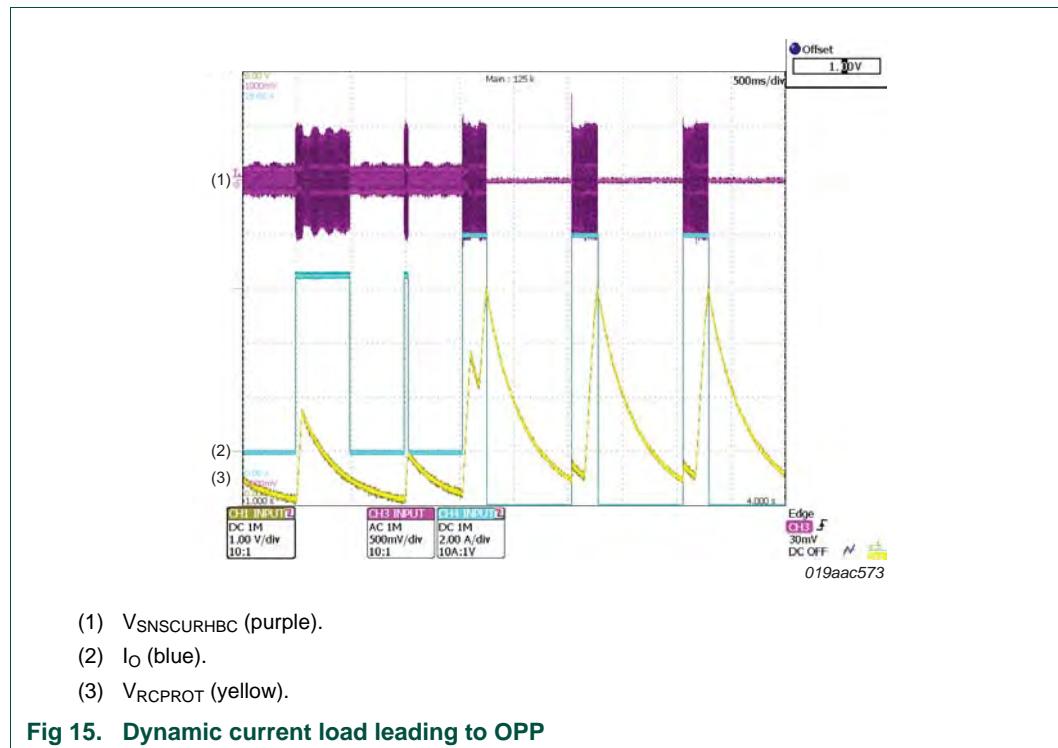
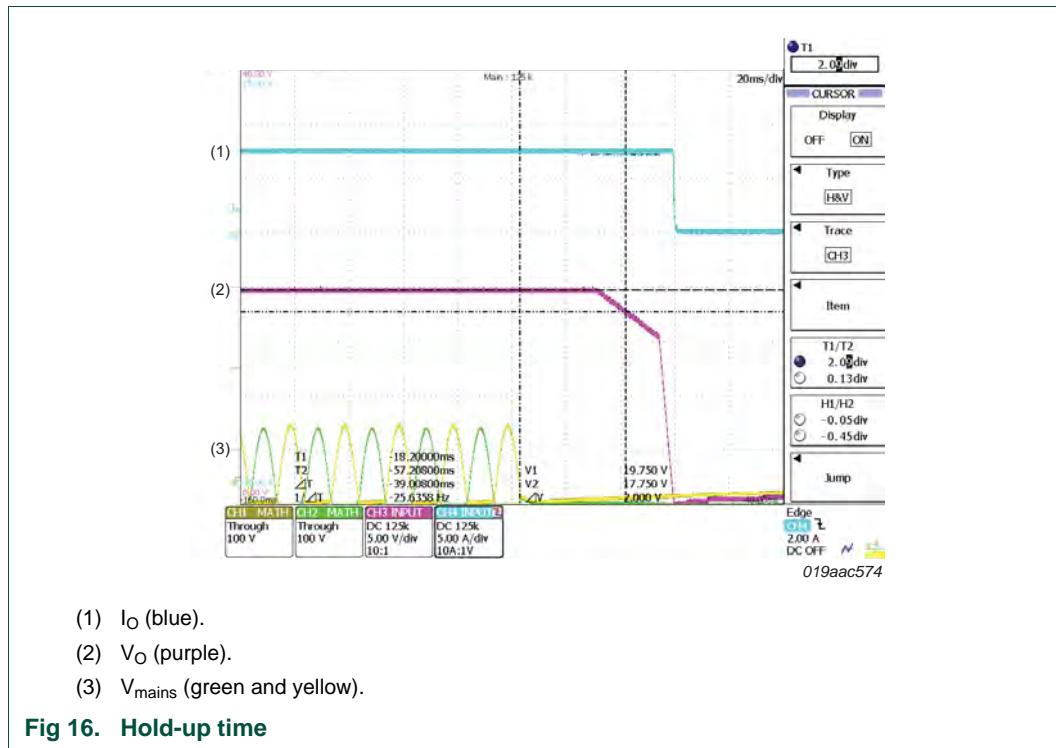


Fig 15. Dynamic current load leading to OPP

2.9 Hold-up time

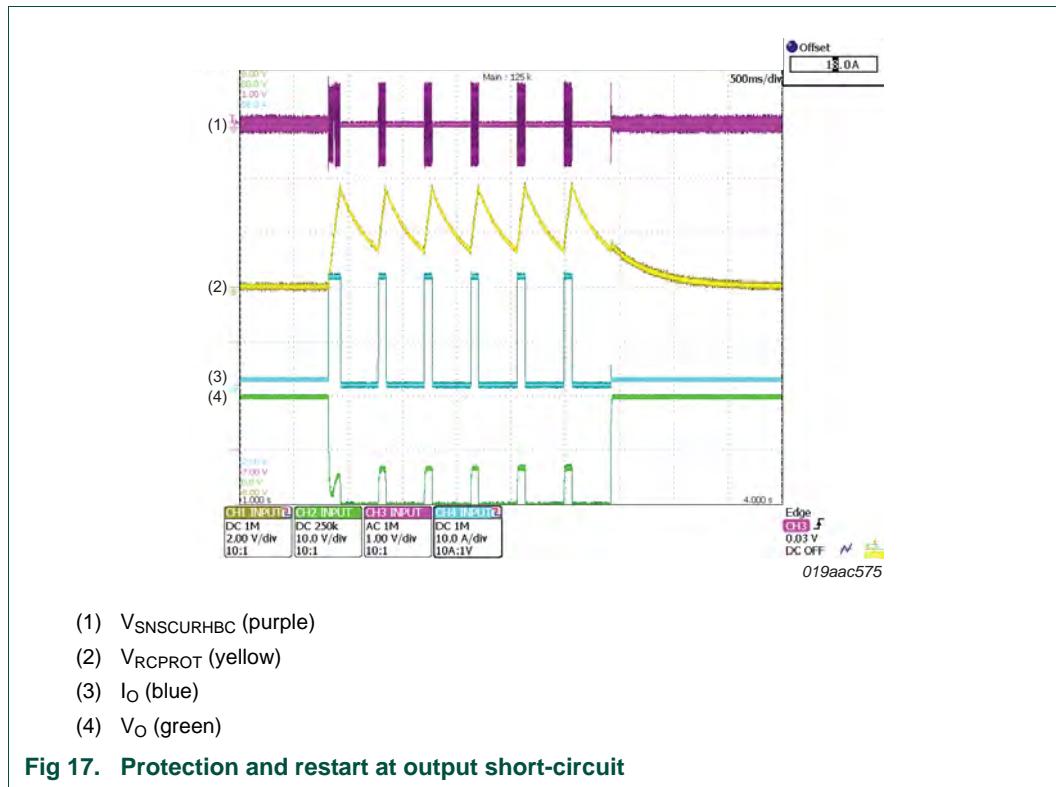
The output is set to full load and the mains supply voltage of 100 V is disconnected. The time that passes before the output voltage falls below 90 % of its initial value is then measured. The hold-up time is 39 ms.



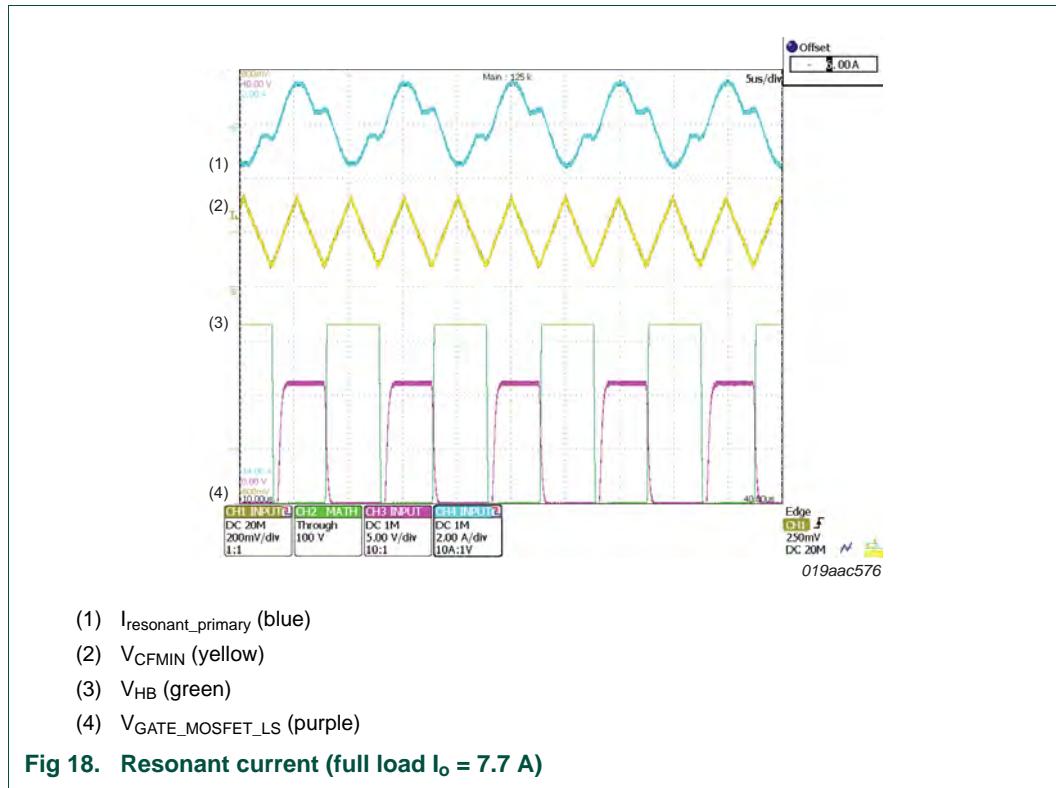
2.10 Short-circuit protection

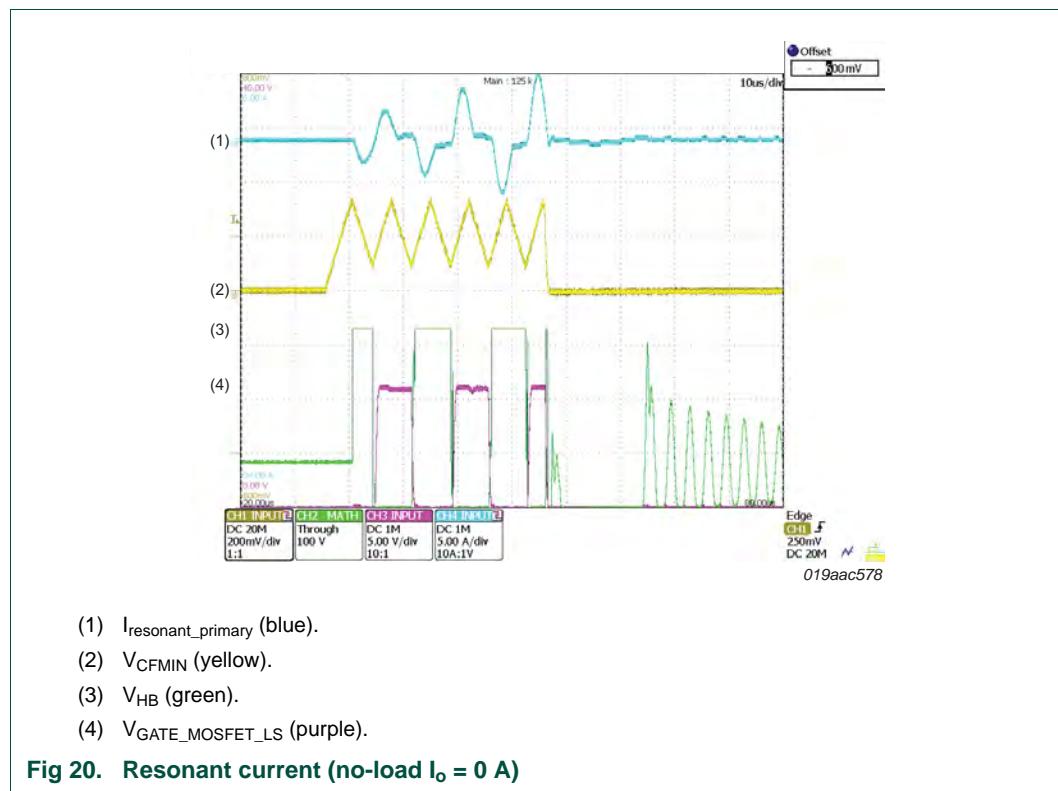
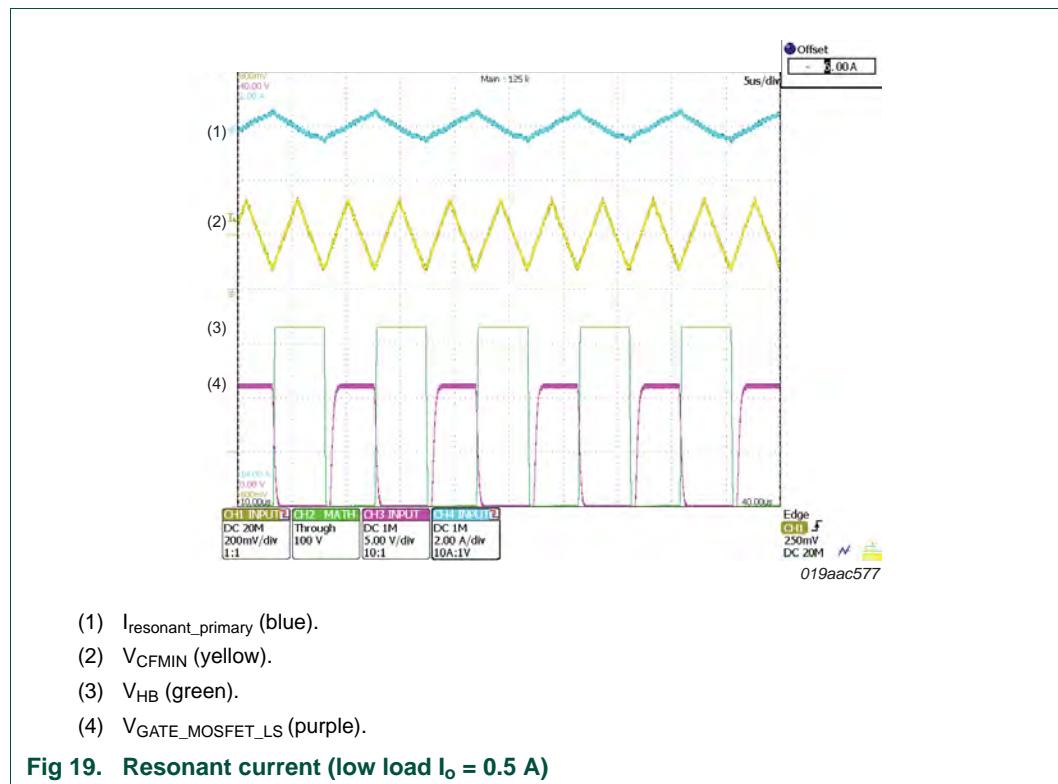
A short circuit on the output of the resonant converter causes the primary current to increase. This is detected by the SNSCURHBC function leading to running on maximum frequency until the protection timer RCPROT reaches its protection level (4 V). The RCPROT function performs its restart timer function and restarts again when the voltage has dropped to 0.5 V. When the short-circuit is removed, the converter starts up and operates as normal.

This is the main protection mechanism. Under certain conditions, other protections can be activated during the output short circuit test.



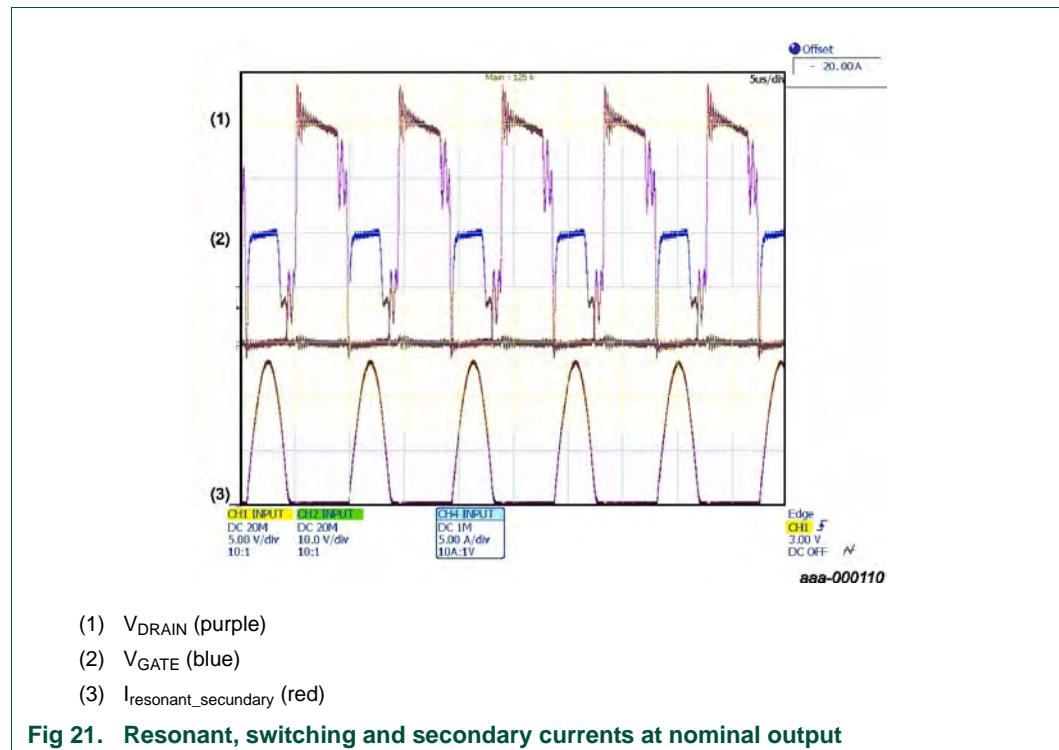
2.11 Resonant current measurements





2.12 Synchronous Rectification

The TEA1795T IC is used for synchronous rectification and replaces the rectifier diodes at the secondary side of the resonant adapter.



3. Circuit diagram

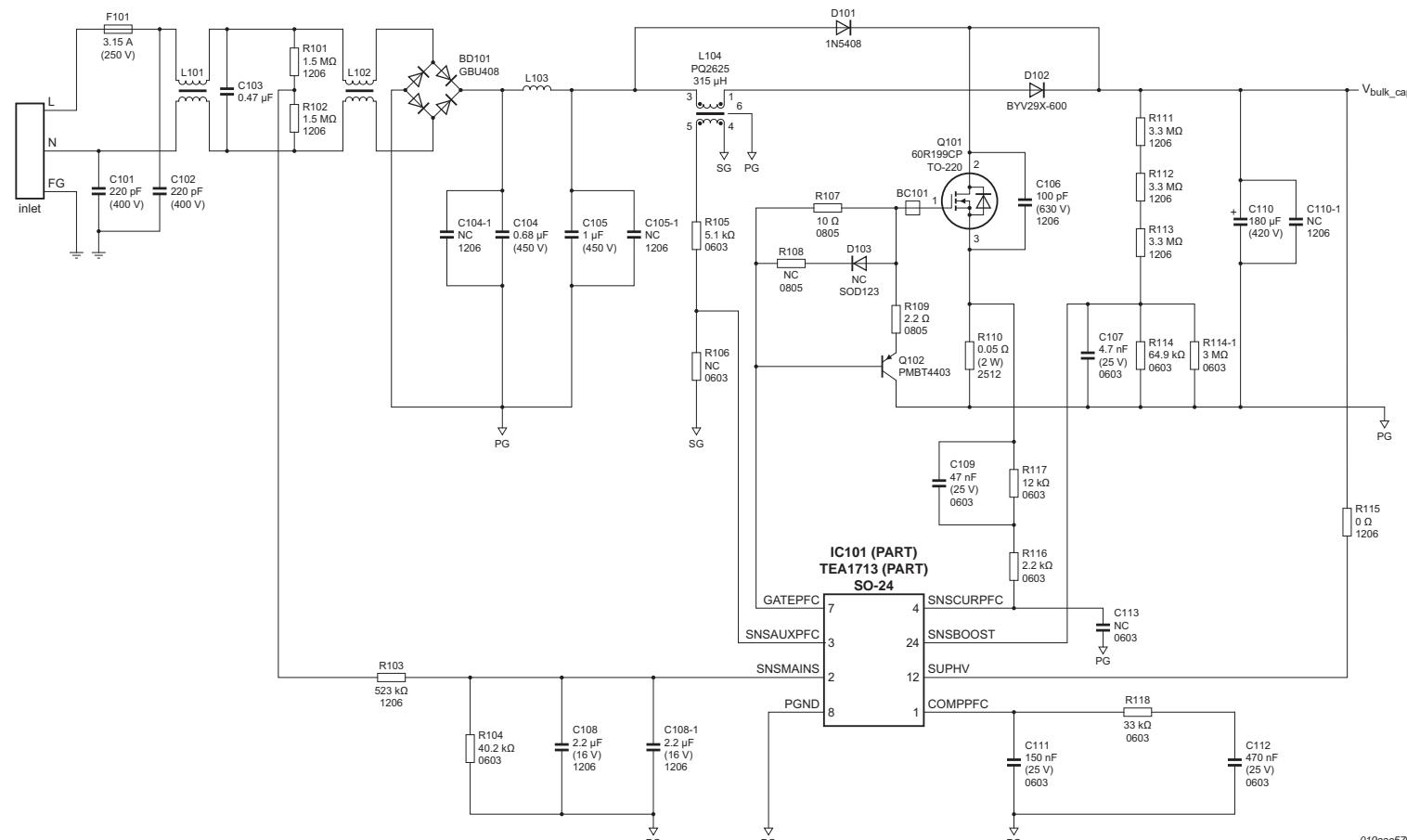
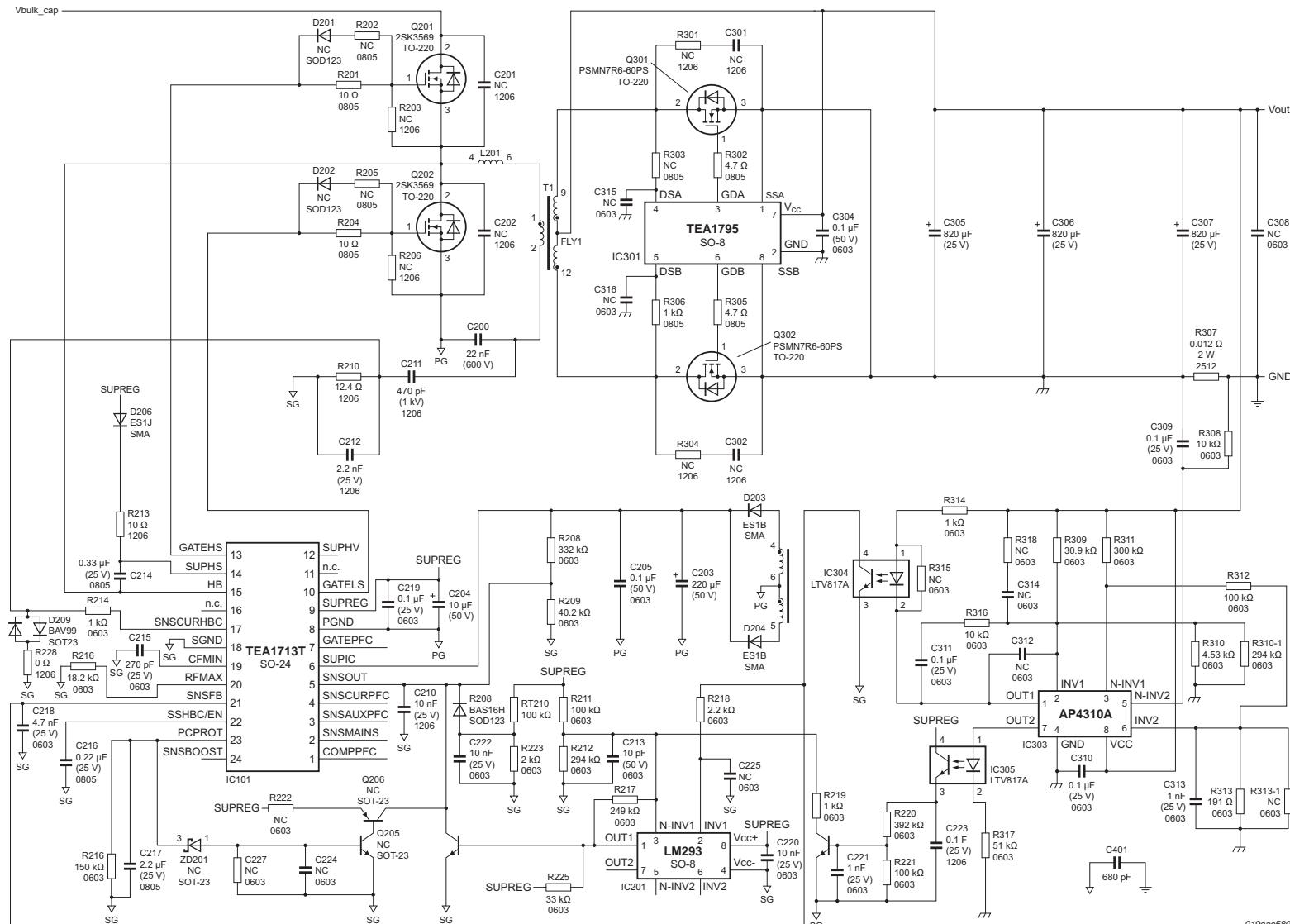
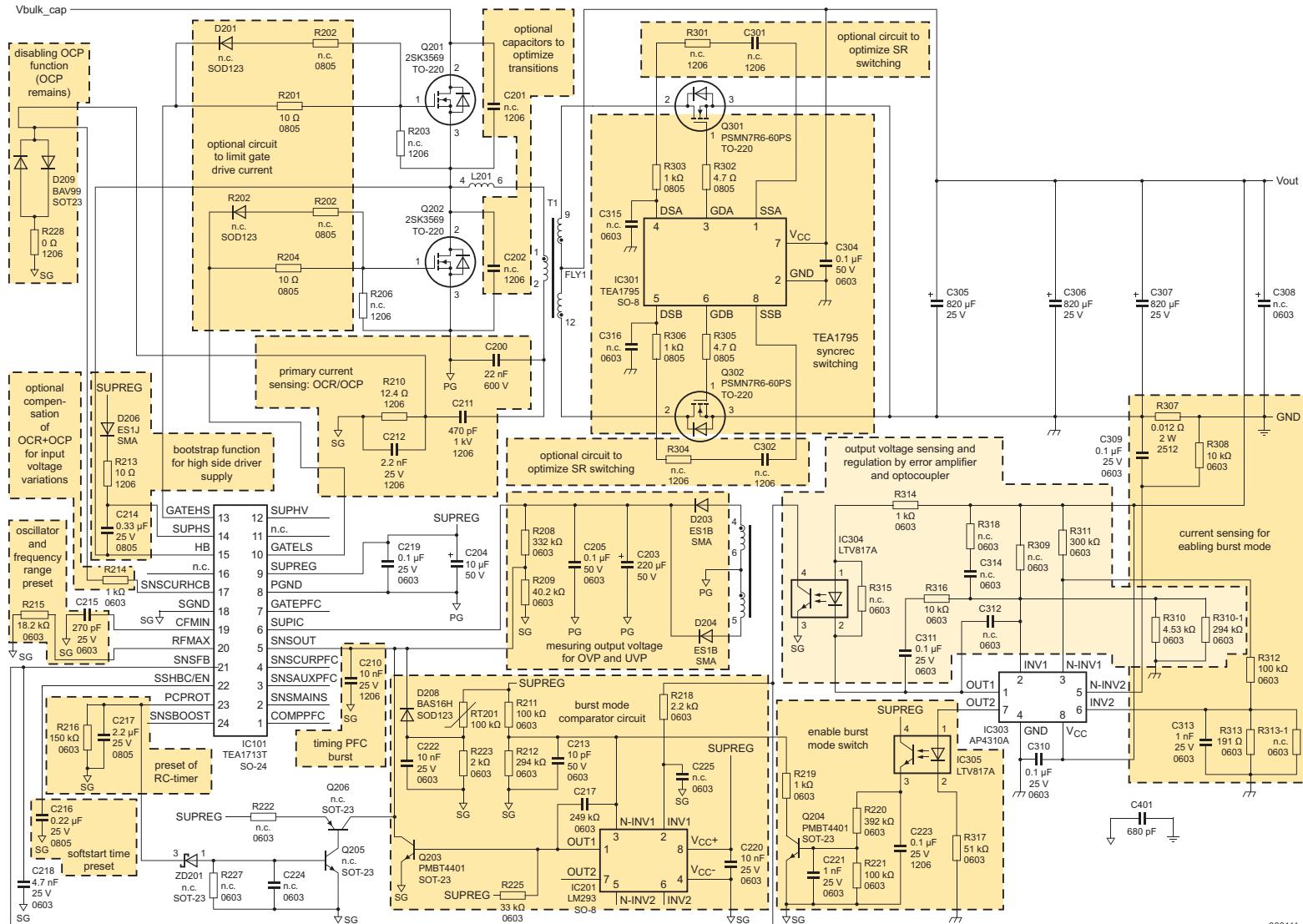


Fig 22. Circuit diagram TEA1713T 150 W demo board (PFC part)

TEA1713 and TEA1795 demo board for 150 W all-in-one PC adapter**Fig 23. Circuit diagram TEA1713T 150 W demo board (HBC part)**

TEA1713 and TEA1795 demo board for 150 W all-in-one PC adapter



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Fig 24. Circuit diagram TEA1713T 150 W demo board (HBC part)

TEA1713 and TEA1795 demo board for 150 W all-in-one PC adapter

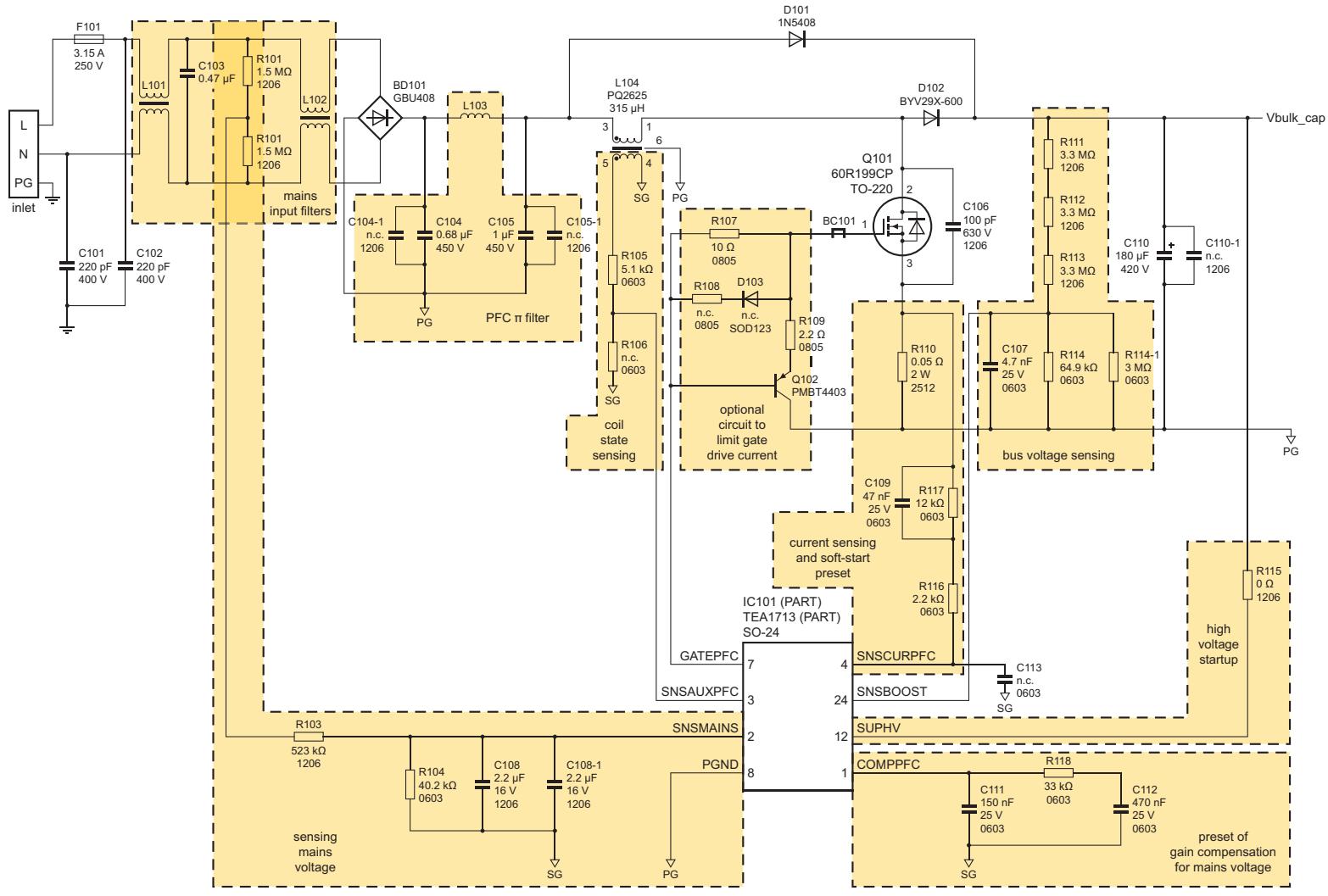


Fig 25. Circuit diagram TEA1713T 150 W demo board (PFC part)

4. PCB layout

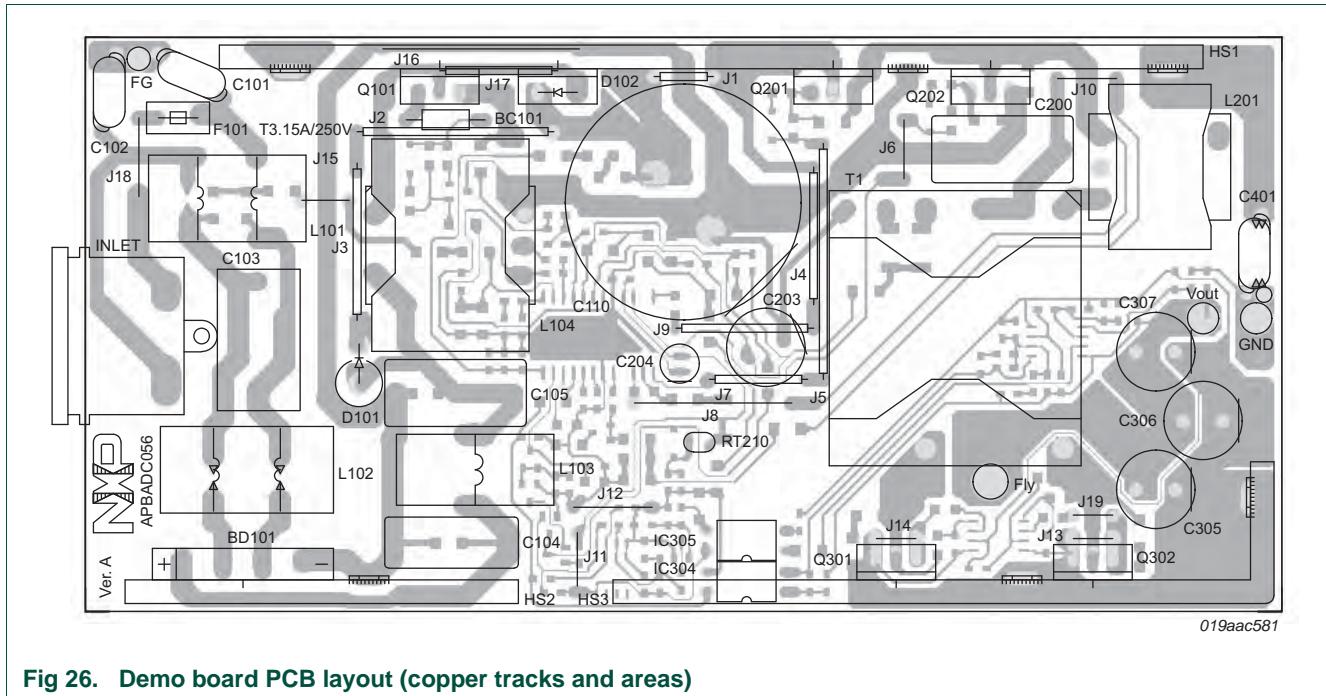


Fig 26. Demo board PCB layout (copper tracks and areas)

5. Bill Of Materials (BOM)

[Table 7](#) provides detailed component information for the TEA1713T and TEA1795T demo board for 150 W all-in-one PC adapter.

Table 7. BOM for the TEA1713T and TEA1795T demo board

Item	Location	Quantity	Description
1	BC101	1	bead core; axial lead; WBRH3.5*4.7*0.8; 3L
2	BD101	1	bridge diode; GBU408; Lite-On 4 A; 800 V
3	C101; C102	2	ceramic; Y1-capacitor; KX/Murata 220 pF; 250 V (AC)
4	C103	1	MKP/HJC; X-capacitor; 0.47 µF; 275 V (AC)
5	C104	1	MPPN/HJC; radial lead 680 nF; 450 V (DC)
6	C105	1	MPPN/HJC; radial lead 1 µF; 450 V (DC)
7	C106	1	MLCC; SMD 1206; NPO; 100 pF; 630 V
8	C107; C218	2	MLCC; SMD 0603; X7R; 4.7 nF; 25 V
9	C108; C108-1	2	MLCC; SMD 1206; X7R; 2.2 µF; 16 V
10	C109	1	MLCC; SMD 0603; X7R; 47 nF; 25 V
11	C110	1	electrolytic capacitor; NCC; 180 µF/420 V; KMQ (W 30 mm × H 25 mm)
12	C111	1	MLCC; SMD 0603; X7R; 150 nF; 25 V
13	C112	1	MLCC; SMD 0603; X7R; 470 nF; 25 V
14	C200	1	MP3/HJC; radial lead 22 nF; 600 V
15	C203	1	E/C; radial lead; 105 °C; 10 × 16 mm; KY/NCC 220 µF; 50 V
16	C204	1	E/C; radial lead; 105 °C; 5 × 11 mm; KY/NCC 10 µF; 50 V

Table 7. BOM for the TEA1713T and TEA1795Tdemo board ...*continued*

Item	Location	Quantity	Description
17	C205; C304	2	MLCC; SMD 0603; X7R; 100 nF; 50 V
18	C210	1	MLCC; SMD 1206; X7R; 10 nF; 25 V
19	C211	1	MLCC; SMD 1206; NPO; 470 pF; 1 kV
20	C212	1	MLCC; SMD 1206; X7R; 2.2 nF; 25 V
21	C213	1	MLCC; SMD 0603; X7R; 10 pF; 50 V
22	C214	1	MLCC; SMD 0805; X7R; 330 nF; 25 V
23	C215	1	MLCC; SMD 0603; X7R; 270 pF; 25 V
24	C216	1	MLCC; SMD 0805; X7R; 220 nF; 25 V
25	C217	1	MLCC; SMD 0805; X7R; 2.2 µF; 25 V
26	C219; C309; C310; C311	4	MLCC; SMD 0603; X7R; 100 nF; 25 V
27	C220; C222	2	MLCC; SMD 0603; X7R; 10 nF; 25 V
28	C221; C313	2	MLCC; SMD 0603; X7R; 1 nF; 25 V
29	C223	1	MLCC; SMD 1206; X7R; 100 nF; 25 V
30	C305; C306; C307	3	electrolytic capacitor; NCC; 820 µF; 25 V; KZH (W 10 mm × H 20 mm)
31	C401	1	ceramic; Y1-capacitor; KX/Murata; 680 pF; 250 V (AC)
32	D101	1	general purpose diode; NXP Semiconductors; 1N5408; 3 A; 1 KV
33	D102	1	ultrafast power diode; BYV29X-600
34	D203; D204	2	ultrafast rectifier; SMA; ES1B; 1 A; 100 V
35	D206	1	ultrafast rectifier; SMA; ES1J; 1 A; 600 V
36	D208	1	high speed switching diode; SOD123F; BAS16H; 100 V
37	D209	1	high speed double diode; SOT23; BAV99; 75 V
38	F101	1	fuse; MST(CONQUER); 3.15 A; 250 V
39	IC101	1	resonant power supply control IC with PFC; NXP Semiconductors; SO24; TEA1713T
40	IC201	1	low power dual voltage comparator; SO8; LM293
41	IC301	1	GreenChip synchronous rectifier controller; SO8; TEA1795T; NXP Semiconductors
42	IC303	1	dual opamp and voltage reference; SO8; AP4310A; BCD
43	IC304; IC305	2	high density mounting type photocoupler; DIP 4; LTV817A; LiteOn
44	Inlet	1	AC inlet 3P
45	L101	1	EMI choke; 7.35 mH; SA382/HJC
46	L102	1	EMI choke; 11.07 mH; SA383/HJC
47	L103	1	filter choke 170 µH; SA384/HJC
48	L104	1	PFC choke; PQ2625/315uH; SA136/HJC
49	L201	1	choke; ATQ2116.8/44 µH; SA135/HJC
50	T1	1	XFMR; PQ3221/800uH; SA137/HJC
51	Q101	1	MOSFET; IPA60R199CP; TO220; Infineon; 16 A; 600 V
52	Q102	1	PNP switching transistor; PMBT4403; SOT23; NXP Semiconductors
53	Q201; Q202	2	MOSFET; 2SK3569; TO220; Toshiba; 10 A; 600 V
54	Q203; Q204	2	NPN switching transistor; SOT23; NXP Semiconductors; PMBT4401
55	Q301; Q302	2	MOSFET; PSMN7R6-60PS; TO220AB; NXP Semiconductors; 92 A; 60 V

Table 7. BOM for the TEA1713T and TEA1795Tdemo board ...*continued*

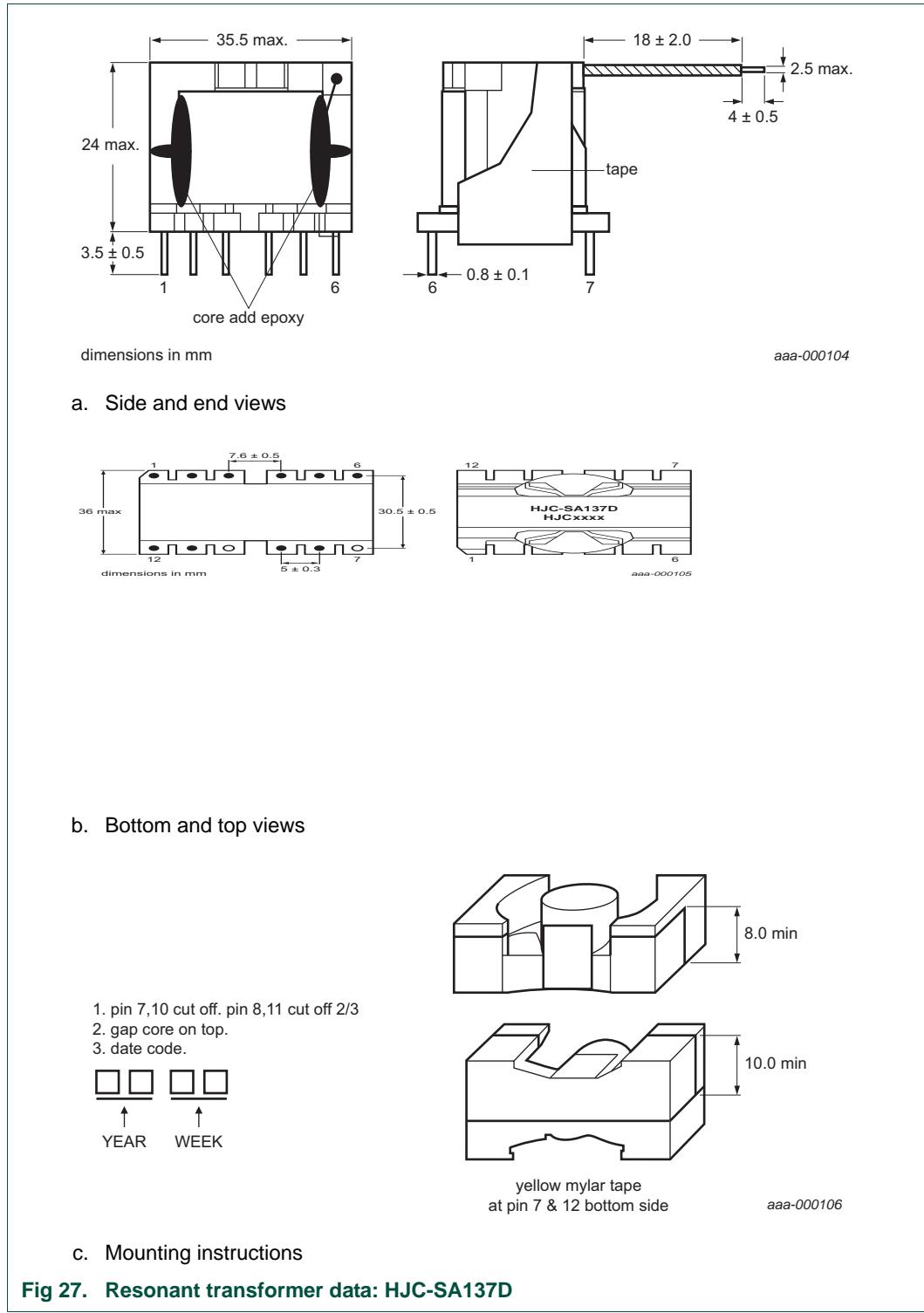
Item	Location	Quantity	Description
56	R101; R102	2	resistor; SMD 1206; thin film; 1.5 MΩ; 5 %
57	R103	1	resistor; SMD 1206; thin film; 523 kΩ; 1 %
58	R104	1	resistor; SMD 0603; thin film; 40.2 kΩ; 1%
59	R105	1	resistor; SMD 0603; thin film; 5.1 kΩ; 1 %
60	R107; R201; R204	3	resistor; SMD 0805; thin film; 10 Ω; 5 %
61	R109	1	resistor; SMD 0805; thin film; 2.2 Ω; 5 %
62	R110	1	resistor; SMD 2512/2W RLP; thin film; 0.05 Ω; 1 %; TAI
63	R111; R112; R113	3	Resistor; SMD 1206; thin film; 3.3 MΩ; 1 %
64	R114	1	resistor; SMD 0603; thin film; 64.9 kΩ; 1 %
65	R114-1	1	resistor; SMD 0603; thin film; 3 MΩ; 1 %
66	R115; RJ1; RJ2; RJ3; RJ4; RJ5; RJ6; RJ7; RJ8; RJ9; RJ10; RJ11; RJ12; RJ13; RJ14; RJ15; R228	17	resistor; SMD 1206; thin film; 0 Ω; 5 %
67	R214; R219; R314	3	resistor; SMD 0603; thin film; 1 KΩ; 1 %
68	R117	1	resistor; SMD 0603; thin film; 12 kΩ; 5 %
69	R118; R225	2	resistor; SMD 0603; thin film; 33 kΩ; 5 %
70	R208	1	resistor; SMD 0603; thin film; 332 kΩ; 1 %
71	R209	1	resistor; SMD 0603; thin film; 40.2 kΩ; 1 %
72	R210	1	resistor; SMD 1206; thin film; 12.4 Ω; 1 %
73	R213	1	resistor; SMD 1206; thin film; 10 Ωm; 1 %
74	R211; R221; R312	3	resistor; SMD 0603; thin film; 100 kΩ; 1 %
75	R212	1	resistor; SMD 0603; thin film; 294 kΩ; 1 %
76	R215	1	resistor; SMD 0603; thin film; 18.2 kΩ; 1 %
77	R216	1	resistor; SMD 0603; thin film; 150 kΩ; 1 %
78	R217	1	resistor; SMD 0603; thin film; 249 kΩ; 1 %
79	R116; R218	2	resistor; SMD 0603; thin film; 2.2 kΩ; 5 %
80	R220	1	resistor; SMD 0603; thin film; 392 kΩ; 1 %
81	R223	1	resistor; SMD 0603; thin film; 2 kΩ; 1 %
82	R308; R316	2	resistor; SMD 0603; thin film; 10 kΩ; 1 %
83	RT201	1	NTC thermistor; TTC3A104F4192EY; Thinking; 100 kΩ; 1 %
84	R302; R305	2	resistor; SMD 0805; thin film; 4.7 Ω; 5 %
85	R303; R306	2	resistor; SMD 0805; thin film; 1 kΩ; 1 %
86	R307	1	resistor; SMD 2512/2W RLP; TAI; thin film; 12 mΩ; 1 %
87	R309	1	resistor; SMD 0603; thin film; 30.9 kΩ; 1 %
88	R310	1	resistor; SMD 0603; thin film; 4.53 kΩ; 1 %
89	R310-1	1	resistor; SMD 0603; thin film; 294 kΩ; 1 %
90	R311	1	resistor; SMD 0603; thin film; 300 kΩ; 1 %
91	R313	1	resistor; SMD 0603; thin film; 191 Ω; 1 %
92	R317	1	resistor; SMD 0603; thin film; 51 kΩ; 1 %

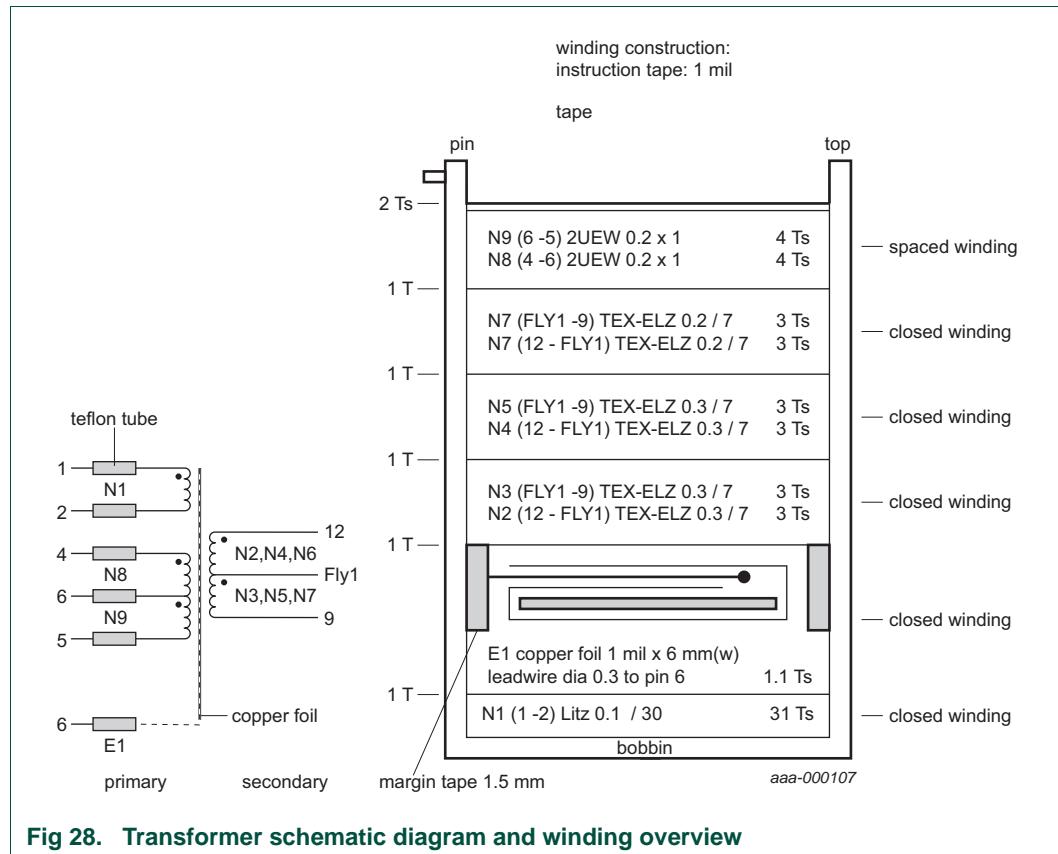
Table 7. BOM for the TEA1713T and TEA1795Tdemo board ...*continued*

Item	Location	Quantity	Description
93	HS1	1	heatsink-HS1 for Q101; D102; Q201; Q202
94	HS2	1	heatsink-HS2; for BD101
95	HS3	1	heatsink-HS3; for Q301; Q302

6. Appendix 1 - Resonant transformer data

6.1 Transformer diagram





6.2 Transformer electrical specification

Table 8. Electrical specification

See [Table note 1](#), [Table note 2](#) and [Table note 3](#) for the relevant measuring conditions.

Parameter	Start	Finish	Specification
Inductance ^[1]	1	2	800 μ H; $\pm 3\%$
Leakage inductance ^[1]	1	1	sec short; 15 μ H maximum
DC resistance ^[2]	1	2	165 m Ω maximum
	4	5	490 m Ω maximum
	12	fly1	6.10 m Ω maximum
Voltage ratio ^[3] ; input 1, 2	4	5	2.58 V (RMS) ± 0.08 V (RMS)
	12	fly1	0.975 V (RMS) ± 0.08 V (RMS)
	fly1	9	0.975 V (RMS) ± 0.08 V (RMS)

[1] Measured with HP: 4284A LCR meter (or equivalent), f = 100 kHz, V = 1 V (RMS) at 25 °C.

[2] Measured with CHEN HWA 502 AC meter (or equivalent) at 25 °C.

[3] Measured with CHEN HWA 310 meter (or equivalent); 20 kHz, 10 V (RMS).

7. Appendix 2 - PFC coil data

7.1 Transformer schematic diagram and winding specification

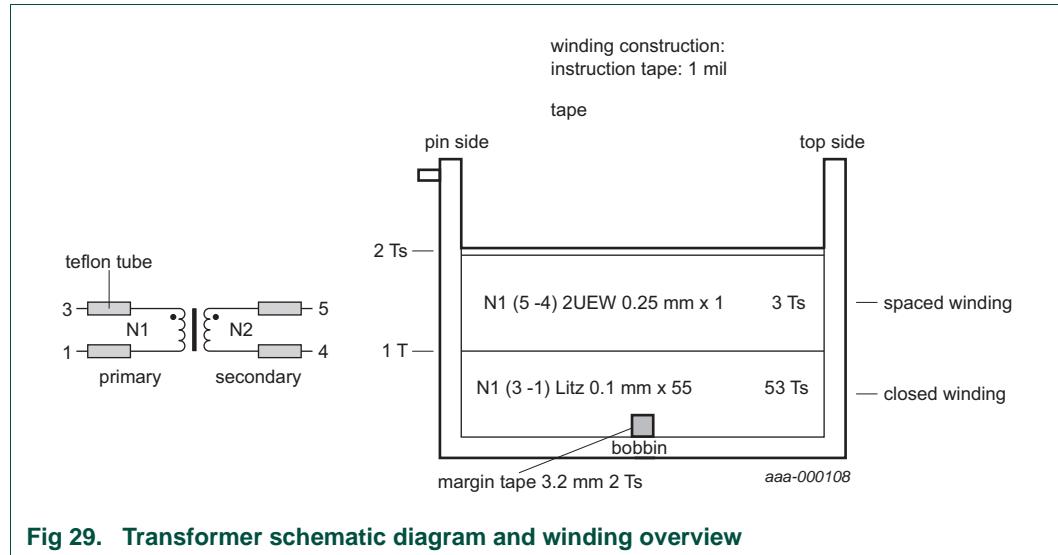


Fig 29. Transformer schematic diagram and winding overview

7.2 Transformer electrical specification

Table 9. Electrical specification

See [Table note 1](#) for the relevant measuring conditions.

Parameter	Start	Finish	Specification
Inductance ^[1]	3	1	315 μ H; $\pm 3\%$
Leakage inductance ^[1]	3	1	not applicable

[1] Measured with HP: 4284A LCR meter (or equivalent), f = 100 kHz, V = 1 V (RMS) at 25 °C.

7.3 Core, bobbin and marking

Core and bobbin:

- Core: PQ2625 (JPP-44A)
- Bobbin: PM9820
- Ae: 120 mm²

Marking:

- HJC-SA136A

8. Appendix - Choke coil data

8.1 Choke coil schematic diagram and winding specification

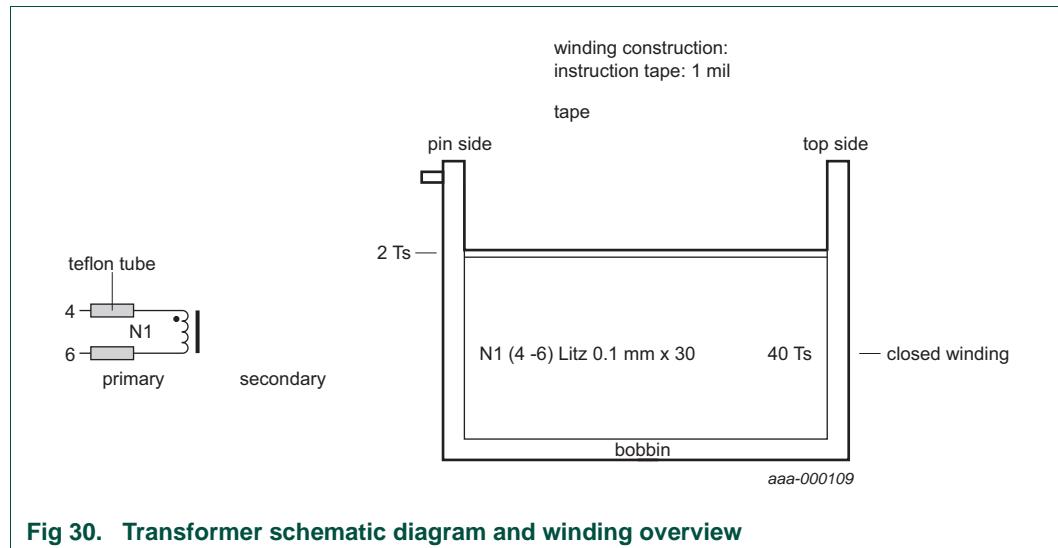


Fig 30. Transformer schematic diagram and winding overview

8.2 Transformer electrical specification

Table 10. Electrical specification

See [Table note 1](#) and [Table note 2](#) or the relevant measuring conditions.

Parameter	Start	Finish	Specification
Inductance ^[1]	4	6	44 μ H; $\pm 3\%$
Leakage inductance ^[1]	3	1	not applicable
DC resistance ^[2]	4	6	145 M Ω maximum

[1] Measured with HP: 4284A LCR meter (or equivalent), f = 100 kHz, V = 1 V (RMS) at 25 °C.

[2] Measured with CHEN HWA 502 AC meter (or equivalent) at 25 °C.

8.3 Core, bobbin and marking

Core and bobbin:

- Core: ATQ21/16.8 (JPP-44A)
- Bobbin: PM9820

Marking:

- HJC-SA135

9. Abbreviations

Table 11. Abbreviations

Acronym	Description
BCM	Boundary conduction Mode
CMP	Capacitive Mode Protection
EMC	ElectroMagnetic Compatibility
EMI	ElectroMagnetic Interference
HBC	Half-Bridge resonant Converter
MOSFET	Metal-Oxide Semiconductor Field-Effect Transistor
OCP	OverCurrent Protection
OPP	OverPower Protection
OVP	OverVoltage Protection
OLP	Open-Loop Protection
PCB	Printed-Circuit Board
PFC	Power Factor Correction
SOI	Silicon-On-Insulator
ZVS	Zero Voltage Switching

10. References

- [1] **TEA1713T** — data sheet - resonant power supply control IC with PFC
- [2] **TEA1795T** — data sheet - GreenChip synchronous rectifier
- [3] **AN10881** — application note - resonant power supply control IC with PFC
- [4] **UM10379** — user manual - 250 W LCD-TV demo board
- [5] **UM10450** — user manual - 90 W notebook adaptor demo board
- [6] **Calculation sheet** — http://www.nxp.com/technical_support/designportal/l1c

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